

2SJ539

Silicon P Channel MOS FET

REJ03G0886-0300

(Previous: ADE-208-657A)

Rev.3.00 Sep 07, 2005

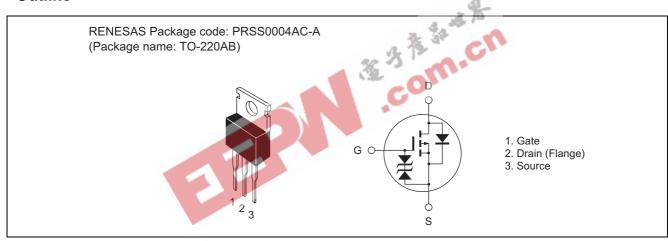
Description

High speed power switching

Features

- Low on-resistance $R_{DS \; (on)} = 0.16 \; \Omega \; typ. \label{eq:DS}$
- Low drive current
- 4 V gate drive devices
- High speed switching

Outline



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Value	Unit
Drain to source voltage	V _{DSS}	-60	V
Gate to source voltage	V_{GSS}	±20	V
Drain current	I _D	-10	Α
Drain peak current	I _{D (pulse)} Note 1	-40	Α
Body to drain diode reverse drain current	I _{DR}	-10	Α
Avalanche current	I _{AP} Note 3	-10	Α
Avalanche energy	E _{AR} Note 3	8.5	mJ
Channel dissipation	Pch Note 2	40	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes: 1. PW \leq 10 μ s, duty cycle \leq 1%

2. Value at $Tc = 25^{\circ}C$

3. Value at Tch = 25°C, Rg \geq 50 Ω

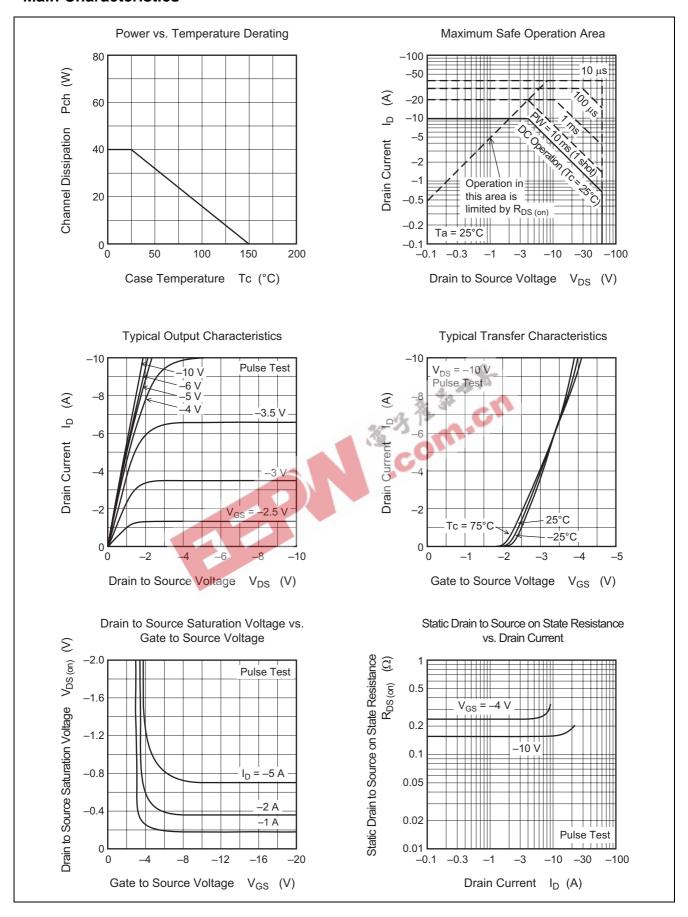
Electrical Characteristics

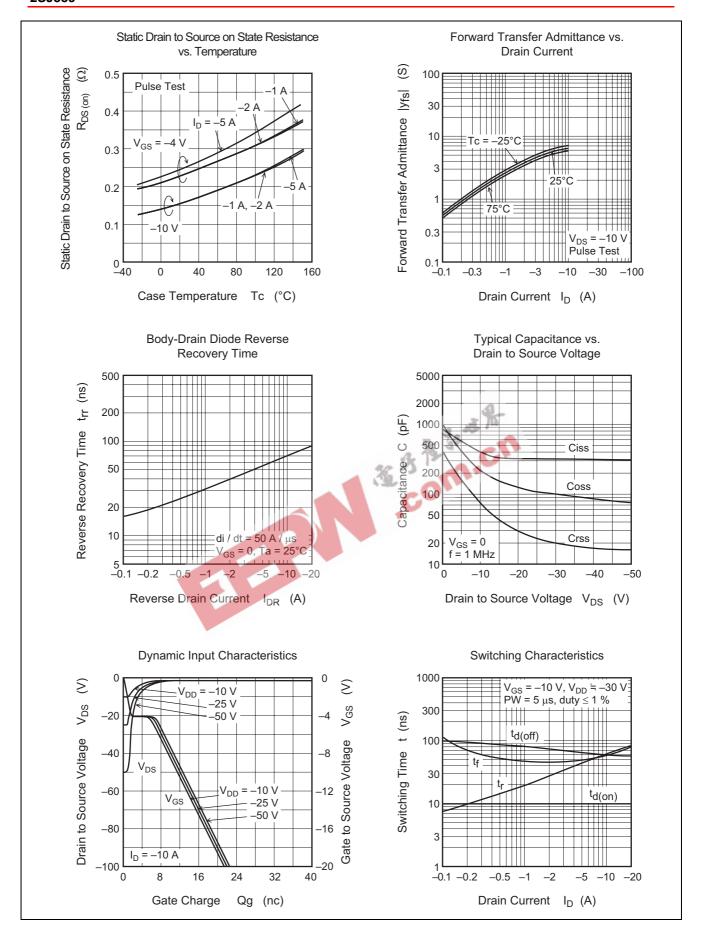
 $(Ta = 25^{\circ}C)$

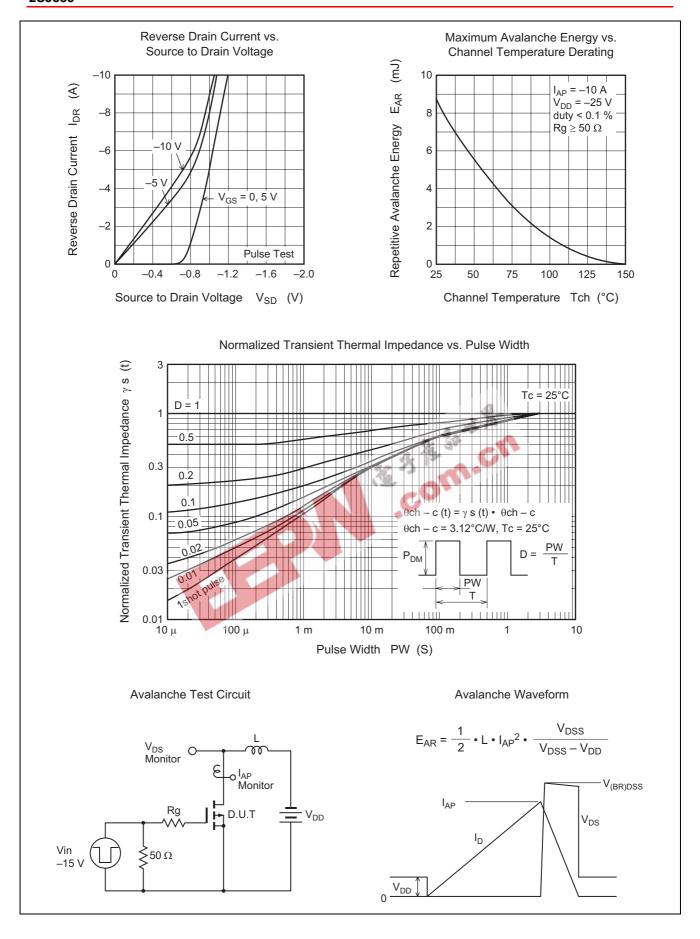
Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage	V _{(BR) DSS}	-60	_		- V	$I_D = -10 \text{ mA}, V_{GS} = 0$
Gate to source breakdown voltage	V _{(BR) GSS}	±20	_	-40	V	$I_G = \pm 100 \mu\text{A}, V_{DS} = 0$
Zero gate voltage drain current	I _{DSS}	_	-2	-10	μΑ	$V_{DS} = -60 \text{ V}, V_{GS} = 0$
Gate to source leak current	I _{GSS}	_	%^	±10	μΑ	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0$
Gate to source cutoff voltage	V _{GS (off)}	-1.0	- JL	-2.0	V	$I_D = -1 \text{ mA}, V_{DS} = -10 \text{ V}$
Static drain to source on state resistance	R _{DS} (on)	4	0.16	0.21	Ω	$I_D = -5 \text{ A}, V_{GS} = -10 \text{ V}^{\text{Note 4}}$
	R _{DS (on)}	Į	0.23	0.36	Ω	$I_D = -5 \text{ A}, V_{GS} = -4 \text{ V}^{\text{Note 4}}$
Forward transfer admittance	y _{fs}	3.5	5.5	_	S	$I_D = -5 \text{ A}, V_{DS} = -10 \text{ V}^{\text{Note 4}}$
Input capacitance	Ciss	_	400	_	pF	$V_{DS} = -10 \text{ V}$
Output capacitance	Coss	_	220	_	pF	$V_{GS} = 0$
Reverse transfer capacitance	Crss	_	75	_	pF	f = 1 MHz
Turn-on delay time	t _{d (on)}	_	10	_	ns	$V_{GS} = -10 \text{ V}$
Rise time	t _r	_	45	_	ns	$I_D = -5 A$
Turn-off delay time	t _{d (off)}	_	65	_	ns	$R_L = 6 \Omega$
Fall time	t _f	_	50	_	ns	
Body to drain diode forward voltage	V_{DF}	_	-1.2	_	V	$I_F = -10 \text{ A}, V_{GS} = 0$
Body to drain diode reverse recovery time	t _{rr}	_	70	_	ns	$I_F = -10 \text{ A}, V_{GS} = 0$
						$di_F/dt = 50 A/\mu s$

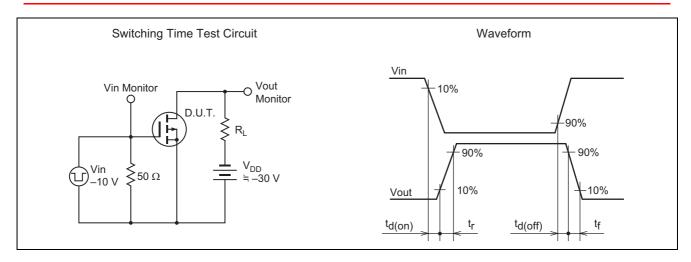
Note: 4. Pulse test

Main Characteristics



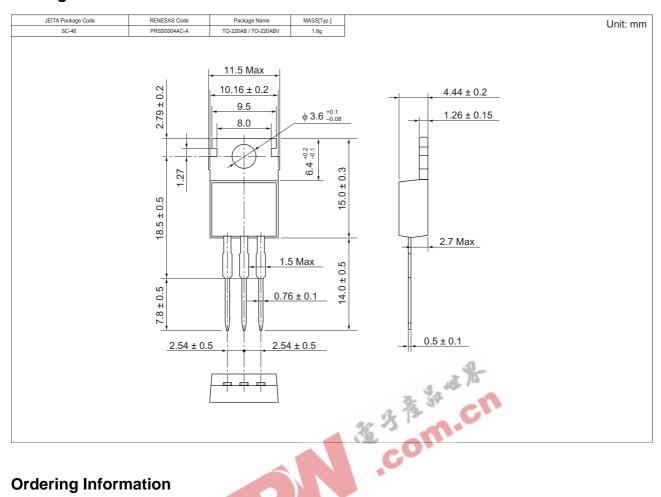








Package Dimensions



Ordering Information

Part Name	Quantity	Shipping Container
2SJ539-E	500 pcs	Box (Sack)

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